



CMP CONSUMABLES

EQUIPMENT COMPONENTS 2014

Techcet Group Critical Materials Report

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Techcet Group Report

CMP Consumables - 2014

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Reader's Please Note: This report represents the interpretation and analysis of information generally available to the public or released by responsible agencies and/or individuals. Data was obtained from sources considered reliable. Any statement that may be considered to be "forward thinking" is not a guarantee and not intended to influence the reader's financial interest nor position. The global semiconductor industry has historically been cyclical due to several factors including changes in customer demand on all levels including end-user demands. Future events are affected by the global economy and the periodic and unpredictable volatile nature of the semiconductor, microelectronics, and nanofabrication industries. C#CMPAMAT08262014 Page | 3

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